

Abstract

A method for forming a back-drilled plated through hole in a printed circuit board and the resulting printed circuit board are described herein. In the preferred embodiment, the printed circuit board includes a via extending through a plurality of stacked layers. The via includes a plated through hole and a back-drilled hole. The plated through hole is located within a predetermined number of the stacked layers and the back-drilled hole is located within the remaining stacked layer(s). The plated through hole without an electrically conductive material located on walls therein has a diameter that is substantially the same size or smaller than the diameter of the back-drilled hole.

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